

Features

- 2550 Watts Peak Pulse Power per Line ($t_p = 8/20\mu s$)
- Protects one I/O or power line
- Low Clamping Voltage
- Working Voltage: 4.7 V
- Low Leakage Current
- Response Time is Typically < 1 ns



IEC COMPATIBILITY (EN61000-4)

- IEC 61000-4-2 (ESD) $\pm 30kV$ (air), $\pm 30kV$ (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 170A (8/20 μs)

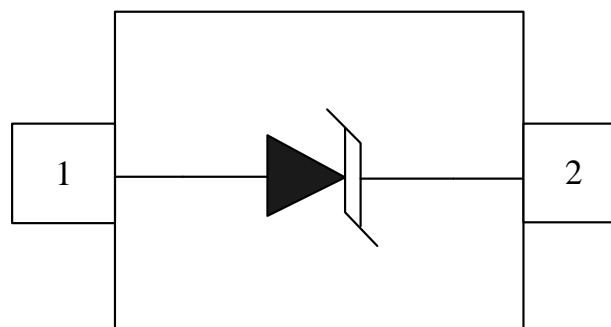
Mechanical Characteristics

- JEDEC SOD-323F package
- Molding compound flammability rating: UL 94V-0
- Marking : Marking Code
- Packaging : Tape and Reel per EIA 481
- RoHS Compliant

Applications

- Laptop Computers
- Cellular Phones
- Digital Cameras
- Personal Digital Assistants (PDAs)

Schematic & PIN Configuration

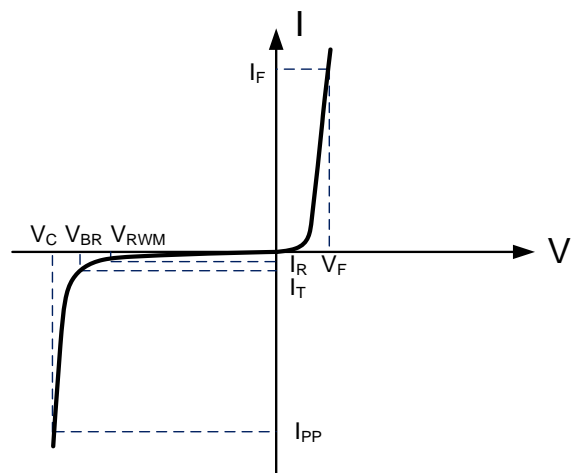


SOD-323F (Top View)

Absolute Maximum Rating			
Rating	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{PP}	2550	Watts
Peak Pulse Current ($t_p = 8/20\mu s$)	I_{PP}	170	A
Operating Temperature	T_J	-55 to + 125	$^{\circ}C$
Storage Temperature	T_{STG}	-55 to +150	$^{\circ}C$

Electrical Parameters (T=25°C)

Symbol	Parameter
I_{PP}	Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Reverse Stand-Off Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_F	Forward Current
V_F	Forward Voltage @ I_F



Electrical Characteristics

WS4.5D3HV						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V_{RWM}				4.7	V
Reverse Breakdown Voltage	V_{BR}	$I_T = 1mA$	4.8		7.0	V
Forward Voltage	V_F	$I_F = 10 mA$	0.6		1.0	V
Reverse Leakage Current	I_R	$V_{RWM} = 4.7V, T = 25^{\circ}C$			500	nA
Clamping Voltage	V_C	$I_{PP} = 1A, t_p = 8/20\mu s$			8.5	V
Clamping Voltage	V_C	$I_{PP} = 170A, t_p = 8/20\mu s$			15	V
Dynamic Resistance ^{1,2}	R_{DYN}	$TLP = 0.2/100ns$		0.05		Ω
Junction Capacitance	C_j	$V_R = 0V, f = 1MHz$		485	600	pF

Notes : 1、 TLP Setting : $t_p = 100ns, t_r = 0.2ns, I_{TLP}$ and V_{TLP} sample window: $t_1 = 70ns$ to $t_2 = 90ns$.
 2、 Dynamic resistance calculated from $I_{PP} = 4A$ to $I_{PP} = 16A$ using "Best Fit".

Typical Characteristics

Figure 1: Peak Pulse Power vs. Pulse Time

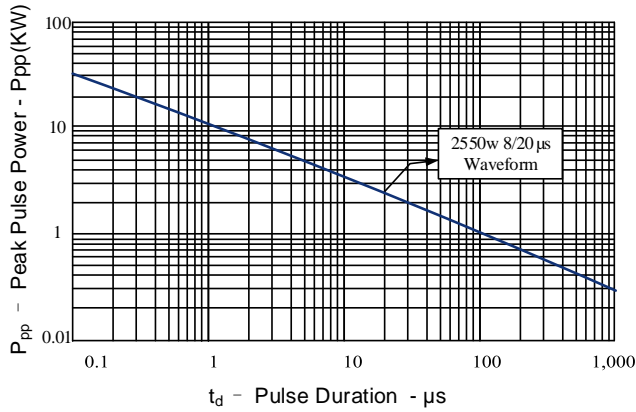


Figure 2: Power Derating Curve

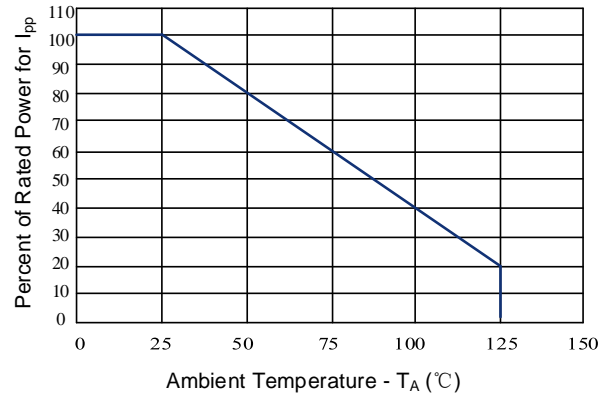


Figure 3: Clamping Voltage vs. Peak Pulse Current

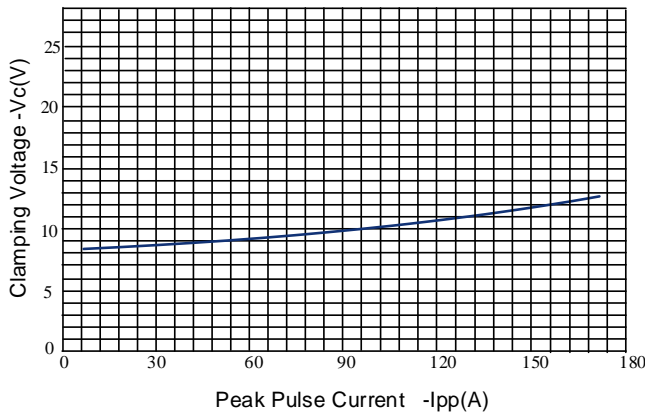


Figure 4: Normalized Junction Capacitance vs. Reverse Voltage

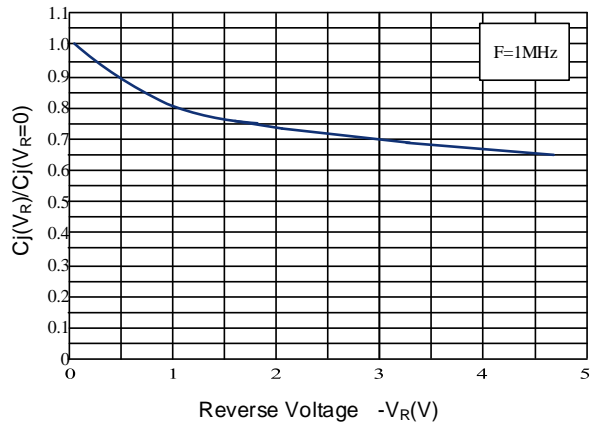


Figure 5: Pulse Waveform

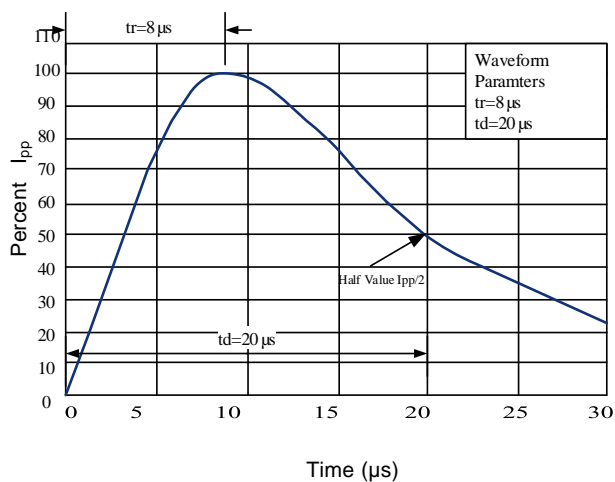
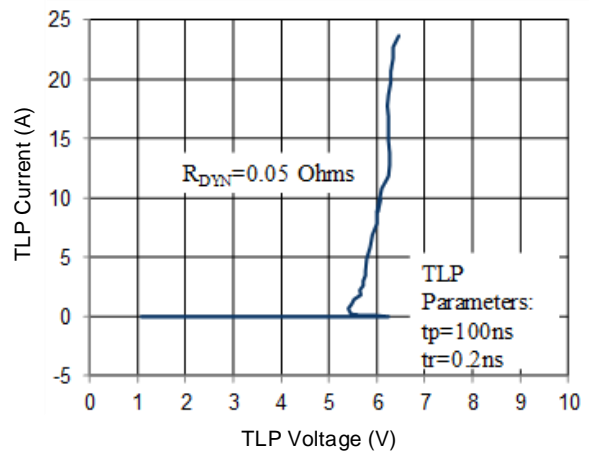
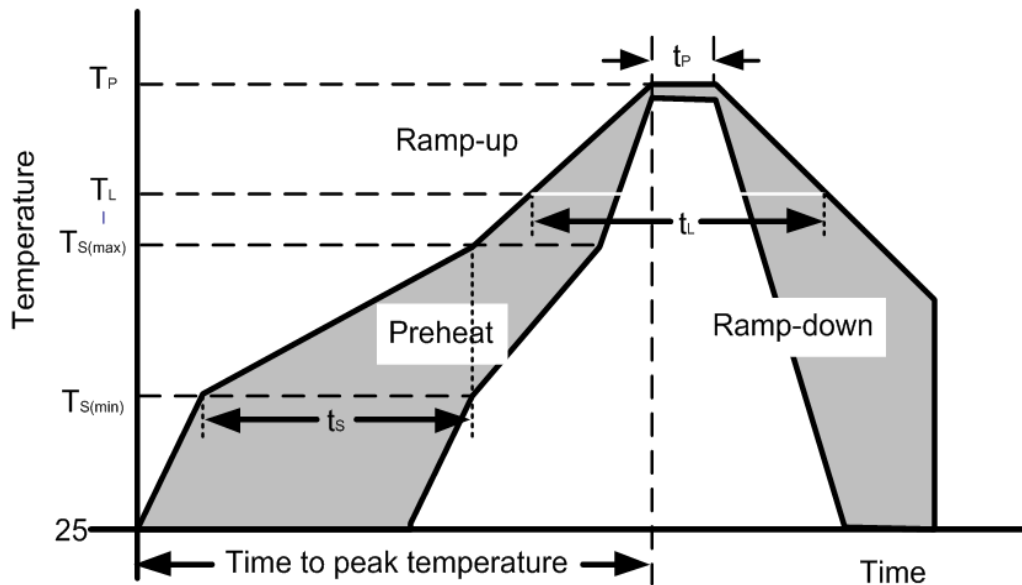


Figure 6: TLP Curve

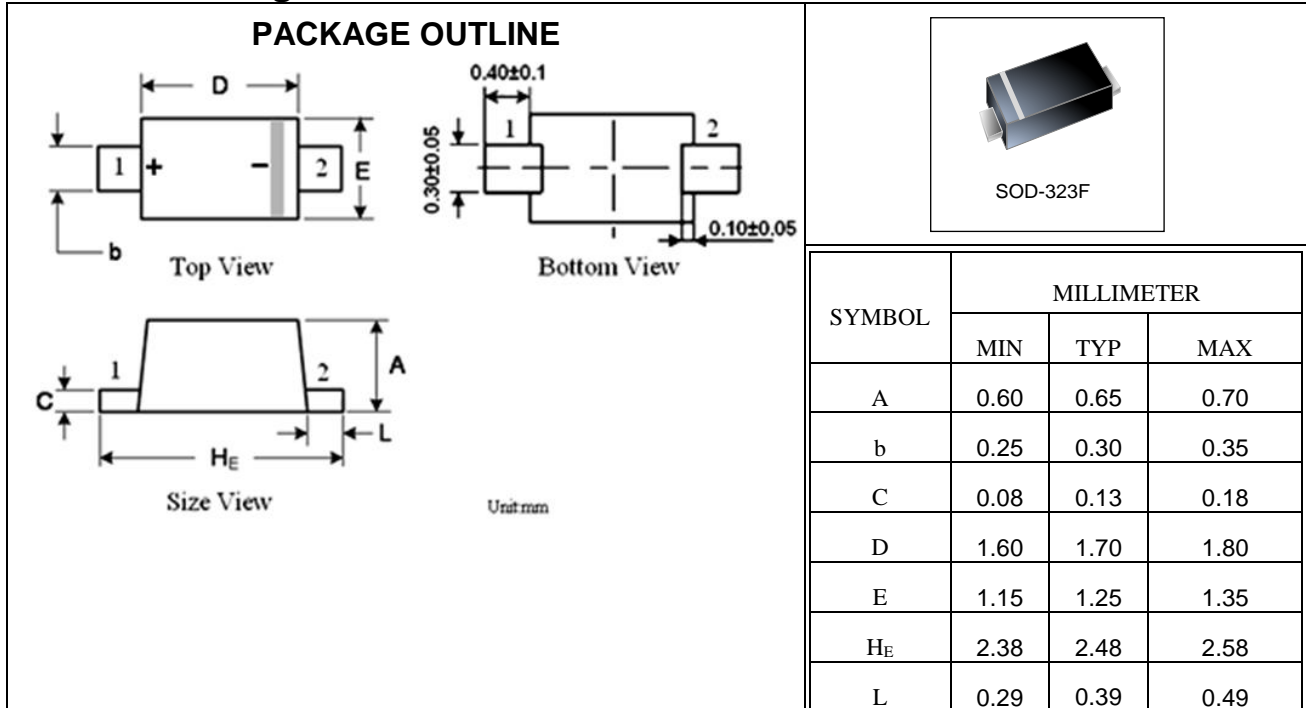


Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	Temperature Min ($T_{S(min)}$)	150°C
	Temperature Max ($T_{S(max)}$)	200°C
	Time (min to max) (t_s)	60 – 190 secs
Average ramp up rate (Liquidus Temp) (T_L) to peak		5°C/second max
$T_{S(max)}$ to T_L —Ramp-up Rate		5°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_P)		260+0/-5 °C
Time within actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.
Do not exceed		280°C

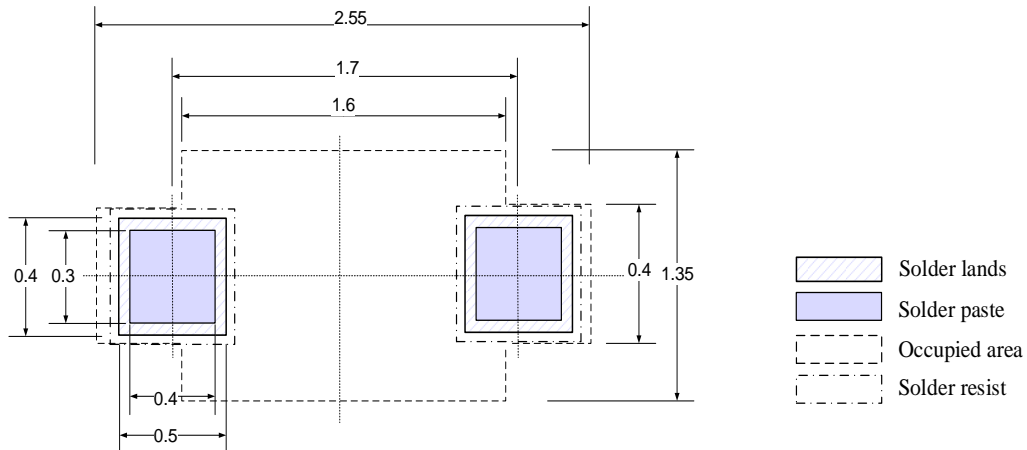


Outline Drawing – SOD-323F



Notes

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL



Unit: mm

Marking Codes

Part Number	Marking Code
WS4.5D3HV	<p>HGX HGX-Specific Device Code X-Month Code</p>

Package Information

Qty: 3k/Reel

CONTACT INFORMATION

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For additional information, please contact your local Sales Representative.

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Specifications are subject to change without notice.
The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.
Users should verify actual device performance in their specific applications.